

# Amphenol® RF

Global RF Solutions

## FEATURES & BENEFITS

Available as AFI-75 for DC-3 GHz 75 Ohm systems  
and AFI-50 for DC-6 GHz 50 Ohm systems

Proprietary configuration that allows for industry  
leading misalignment/"float"

Innovative float system of .030" [0,8 mm] radial  
and .040" [1,0 mm] axial

In-line or Dual-row versions available

## APPLICATIONS

**Military / Aerospace**

**Cable Modem Termination Systems (CMTS)**

**Internet (Routers and Switches)**

**Telecommunications**



## AFI Connectors

# AFI “Amphenol Floating Interface” Connectors

Amphenol RF introduces the AFI connector interface as a solution for blind mate board-to-board RF applications, especially for the military and broadband marketplaces. The AFI interface utilizes a proprietary configuration that allows for industry leading “float” to compensate for the axial and radial misalignment due to packaging tolerances. This industry-leading float results in a maximum misalignment allowed by the system of .030” [0,8 mm] radial and .040” [1,0 mm] axial. The interface is available in both 75 Ohm and 50 Ohm configurations

## AFI - 50 Ohm Specification

### Electrical

Impedance	50 Ω
Frequency Range	DC to 6 GHz
VSWR (Straight Connectors)	-25dB @ 1GHz
RF leakage	-70 dB
Power Handling	95 WATTS

### Mechanical

Engagement Force	0.5 - 5 lbs. max
Disengagement Force	0.5 lbs. min
Connector Durability	100 mating cycles

### Environmental

Temperature Range	-65°C to +165°C
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## AFI - 75 Ohm Specification

### Electrical

Impedance	75Ω
Frequency Range	DC to 3 GHz
VSWR (Straight Connectors)	-25dB @ 1GHz
RF leakage	-70 dB
Power Handling	95 Watts

### Mechanical

Engagement Force	0.5 - 5 lbs. max
Disengagement Force	0.5 lbs. min
Connector Durability	100 mating cycles

### Environmental

Temperature Range	-65°C to +165°C
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## Need AFI Custom I/O Solutions?

Amphenol RF offers two interconnect solutions for both board to board and I/O applications. The proprietary AFI interface solves packaging design issues with its industry leading float which compensates for mechanical misalignment in stacked PCB's and daughter board/mother board applications. The MCX based solution is utilized for I/O or PCB cabled applications with flexible mounting configurations that solve the toughest packaging design constraints.

Please contact your local sales representative for AFI custom solutions.

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